

Form PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTORNEY DOCKET NO. MI22-2308	SERIAL NO. 10/615,051
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)		APPLICANT: Brian A. Vaartstra	
		FILING DATE 7/7/2003	GROUP ART UNIT 2823

*CITE*  
*MAY 04 2005*

U.S. PATENT DOCUMENTS							
*Examiner's Initials		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>BK</i>	AA	6,013,583	1/11/2000	Ajmera et al.			
<i>BK</i>	AB	2001/0041250 A1	11/2001	Haukka et al.			
<i>BK</i>	AC	2002/0000195 A1	1/2002	Kao et al.			
	AD	2003/00129826 A1	7/10/2003	Werkhoven et al.			
<i>BK</i>	AE	2003/0032281 A1	2/13/2003	Werkhoven et al.			
<i>BK</i>	AF	5,770,469	6/1998	Uram et al.			
<i>BK</i>	AG	2004/0266153 A1	12/30/2004	Yongjun Jeff Hu			
	AH						

FOREIGN PATENT DOCUMENTS							
		Document Number	Date	Country	Class	Subclass	Translation
							Yes
<i>BK</i>	AI	EP 0817251 A	1/1998	EPO			
	AJ						No

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)		
	AK	PCT/US2004/021156; Filed 6/30/2004; Search Report.
<i>BK</i>		
<i>BK</i>	AL	PCT/US2004/021156; Filed 6/30/2004; Written Opinion Issued on 1/18/2005; 6 pps.
EXAMINER	DATE CONSIDERED	<i>Brook Kebode 7/5/2005</i>

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Form PTO-1449	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. MI22-2308	SERIAL NO. 10/615,051
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)		APPLICANT: Brian A. Vaartstra	
		FILING DATE 07/07/2003	GROUP 2823

U.S. PATENT DOCUMENTS						
*Examiner's Initials		Document Number	Date	Name	Class	Subclass
	AA					
	AB					
	AC					
	AD					
	AE					

	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
	AP						
	AG						
	AH						

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)						
<i>BK</i>	AI	Chen et al., <i>Excimer Laser-Induced Ti Silicidation to Eliminate the Fine-Line Effect for Integrated Circuitry</i>				
		<i>Device Fabrication</i> , 149 JOURNAL OF ELECTROCHEMICAL SOCIETY, No. 11, pp. G609-G612 (2002).				
<i>BK</i>	AJ	Nishiyama et al., <i>Agglomeration Resistant Self-Aligned Silicide Process Using N<sub>2</sub> Implantation into TiSi<sub>2</sub></i> ,				
		36 JPN. J. APPL. PHYS., Part 1, No. 6A, pp. 3639-3643 (June 1997).				
<i>BK</i>	AK	Wolf, <i>Chapter 13: Polycides and Salicides of TiSix, CoSi<sub>2</sub>, and NiSi, SILICON PROCESSING FOR THE VLSI ERA</i> ,				
		Vol. IV, pp. 603-604 (pre-2003).				
EXAMINER	DATE CONSIDERED <i>Brook Kehinde</i> <i>7/5/2005</i>					
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.						